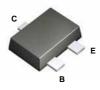




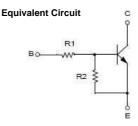
FJY3002R NPN Epitaxial Silicon Transistor

Features

- · Switching circuit, Inverter, Interface circuit, Driver Circuit
- Built in bias Resistor (R1=10kΩ, R2=10kΩ)
- Complement to FJY4002R







Absolute Maximum Ratings * $T_a = 25\%$ unless otherwise noted

Symbol	Parameter	Value	Units
V_{CBO}	Collector-Base Voltage	50	V
V _{CEO}	Collector-Emitter Voltage	50	V
V _{EBO}	Emitter-Base Voltage	10	V
I _C	Collector Current	100	mA
T _{STG}	Storage Temperature Range	-55~150	°C
T _J	Junction Temperature	150	°C
P _C	Collector Power Dissipation, by R _{θJA}	200	mW

С

Thermal Characteristics* T_a=25°C unless otherwise noted

Symbol	Parameter	Max	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	600	°C/W

^{*} Minimum land pad size.

Electrical Characteristics* T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Condition	MIN	Тур	MAX	Units
V _(BR) CBO	Collector-Emitter Breakdown Voltage	Ic = 10 uA, IE = 0	50			V
V _(BR) CEO	Collector-Base Breakdown Voltage	Ic = 100 uA, I _B = 0	50			V
Ісво	Collector-Cutoff Current	Vcb = 40 V, IE = 0			0.1	uA
hfe	DC Current Gain	VcE = 5 V, Ic = 5 mA	30			
Vce(sat)	Collector-Emitter Saturation Voltage	Ic = 10 mA, I _B = 0.5 mA			0.3	V
f⊤	Current Gain - Bandwidth Product	VcE = 10V, Ic = 5 mA		250		MHz
Ccb	Output Capacitance	VcB = 10 V, IE = 0, f = 1.0 MHz		3.7		pF
Vı(off)	Input Off Voltage	Vce = 5 V, Ic = 100uA	0.5			V
V _I (on)	Input On Voltage	VcE = 0.3V, Ic = 10mA			3	V
R ₁	Input Resistor		7	10	13	ΚΩ
R ₁ /R ₂	Resistor Ratio		0.9	1.0	1.1	

^{*} Pulse Test: PW≤300μs, Duty Cycle≤2%

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

Typical Performance Characteristics

Figure 1. DC current Gain

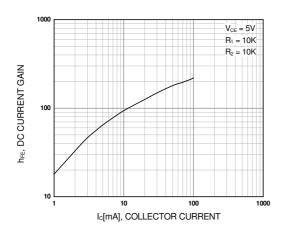


Figure 2. Input On Voltage

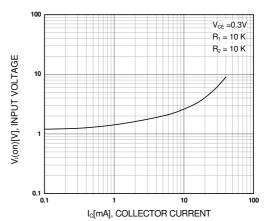


Figure 3. Input off Voltage

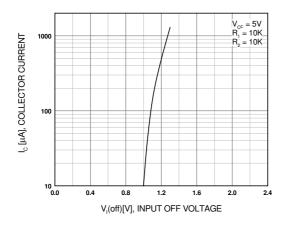
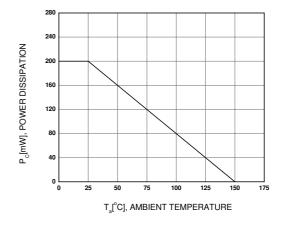
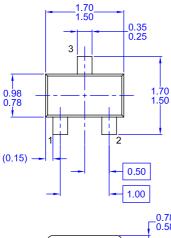


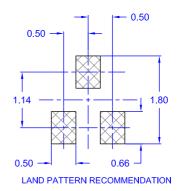
Figure 4. Power Derating

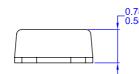


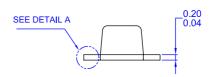
Package Dimensions

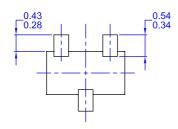
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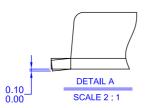












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 C) DIMENSIONS ARE EXCLUSIVE OF BURRS,
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Dimensions in Millimeters



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